

REMARKS

Favorable reconsideration of this application is requested in view of the above amendments and the following remarks. Claims 4-5 and 8-9 are amended for clarification and claims 1-3 are canceled without prejudice or disclaimer. Claims 4-9 remain pending in the case. No new matter has been added. Reconsideration of the claim is respectfully requested.

In paragraph 2 on page 2 of the Office Action, claim 8 was objected to because of informalities and would be allowable if the informalities are corrected. The Applicant respectfully traverses this rejection, but has amended claim 8 as suggested by Examiner to overcome the objection.

Therefore, in view of the above amendment and remarks, Applicant respectfully submits that claim 8 is in condition for allowance.

In paragraph 5 on page 2 of the Office Action, claims 1-3 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Prior Art cited by Applicant's disclosure. According to the Office Action, Applicant's Prior Art reference discloses Applicant's invention substantially as claimed.

Applicant respectfully traverses these rejections, but in the interest of prosecution has canceled claims 1-3 and submits that the rejections are now moot.

In paragraph 6 on page 3 of the Office Action, claim 4 was rejected under 35 U.S.C. § 103(a) as being unpatentable over Sakamoto et al. (U.S. Pat. 6548328). According to the Office Action, Sakamoto discloses Applicant's invention substantially as claimed.

Applicant respectfully traverses this rejection. Applicant respectfully submits that the cited reference does not disclose or suggest the invention. Applicant's invention differs from the cited reference in at least the following respects.

Sakamoto fails to disclose or suggest at least a die bonding pad having the gold layer of the pad being exposed for reflecting light emitted from a light emitting element as recited in claim 4. Rather, in Sakamoto, an upper surface of a pad 51A is almost entirely covered (i.e., not exposed) by a circuit element 52A and intervening material, such as an insulating adhesive or conductive coat (col. 6, lines 29-33; Fig. 1A). Sakamoto does not disclose that the element 52A is a light-emitting device, however, in this arrangement, even if light were emitted from the circuit element 52A, the light would fail to be reflected by the upper surface of the pad 51A because of the intervening materials on the surface of the pad.

Also, as admitted by the Office Action, Sakamoto fails to disclose or suggest that the die bonding pad is generally circular as viewed in plan and having an area larger than a bottom surface area of the light emitting element as recited in claim 4. Applicant respectfully disagrees with the Office Action's assertion that "[t]he limitation of the bonding pad being circular is a non-critical device limitation of the bonding pad." The circular configuration of the reflective pad is useful for reflecting light emitted from a light emitting element.

Therefore, in view of the above remarks, Applicant's independent claim 4 is patentable over the cited reference.

In paragraph 7 on page 4 of the Office Action, claims 5-7 and 9 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Applicant's cited Prior Art, and further in view of Kuhara et al. (U.S. Pat. 6530698). According to the Office Action, Applicant's cited Prior Art discloses Applicant's invention substantially as claimed. However, according to the Office Action, Applicant's cited Prior Art does not teach a recess formed in the surface of the substrate to enhance bonding of the molded resin protection. Nevertheless, according to the Office Action, Kuhara teaches a recess formed in the substrate of a communications module to allow for enhanced bonding of the molded resin to the substrate.

Applicant respectfully traverses this rejection. Applicant respectfully submits that the cited reference does not disclose or suggest the invention.

As admitted by the Office Action, Applicant's cited Prior Art does not disclose or suggest a recess formed in the surface of the substrate to enhance bonding of the molded resin body. Kuhara fails to remedy the deficiencies of Applicant's cited Prior Art as Kuhara fails to disclose or suggest at least that a surface of a substrate is formed with a recess for enhancing bonding between the substrate and the molded body, the recess being completely filled with part of the molded body alone. Kuhara merely shows a recess 7 (Figs. 3 and 4), but this recess is not completely filled with the molded body 14 alone. The recess 7 accommodates not only the molded body 14, but also a fiber 9.

With respect to dependent claim 7, Applicant's invention requires that the recess be generally cylindrical. However, in contrast to the present invention, the groove 7 (or recess) in Kuhara has a V-shaped cross section (col. 1, line 43), whereby the molded body 14 can easily separate from the recess 7. Thus, even in view of the teaching of Kuhara, a person skilled in the

art would not be tempted to modify the Applicant's cited Prior Art to arrive at the present invention.

Therefore, in view of the above remarks, Applicant's independent claim 5 is patentable over the cited references. Applicant's claim 9 also recites a recess on a surface of a substrate wherein the recess is completely filled with the molded resin, and for similar reasons as discussed above, independent claim 9 is believed to be patentable over the cited references.

Because claims 6 and 7 depend directly or indirectly from claim 5 and include the features recited in the independent claim as well as additional features, Applicant respectfully submits that claims 6 and 7 are also patentably distinct over the cited references. Nevertheless, Applicant is not conceding the correctness of the Office Action's rejection with respect to such dependent claims and reserve the right to make additional arguments if necessary.

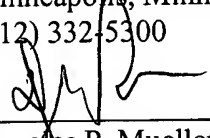
In view of the above amendments and remarks, Applicant respectfully requests a Notice of Allowance. If the Examiner believes a telephone conference would advance the prosecution of this application, the Examiner is invited to telephone the undersigned at the below-listed telephone number.

Respectfully submitted,

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